

Product / Process Change Notification



N° 2015-021-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Implementation of TO220 Fullpak in Nantong Fujitsu Microelectronics Co., Ltd. (NFME) for IGBT and Diode products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **04. August 2015**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change. "

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response within the given time limit we consider this as the acceptance of the PCN.

Product / Process Change Notification



N° 2015-021-A

SUBJECT OF CHANGE: Implementation of TO220 Fullpak in Nantong Fujitsu Microelectronics Co., Ltd. (NFME) for IGBT and Diode products

PRODUCTS AFFECTED: Please refer to 1_cip15021a

REASON OF CHANGE: Infineon Production Strategy to fulfill customers increasing demand for TO220Fullpak products

DESCRIPTION OF CHANGE:	<u>OLD</u>	<u>NEW</u>
■ Assembly fab and final test location	Infineon Technologies (Malaysia) Sdn. Bhd.	Nantong Fujitsu Microelectronics Co., Ltd. (NFME), China
■ Package Visual Appearance	Please refer to 3_cip15021a	

PRODUCT IDENTIFICATION: Traceability ensured via Bau number, Lot number, Date code and Marking on devices

TIME SCHEDULE:

■ Final qualification report:	available
■ First samples available:	30-June-2015
■ Start of delivery:	21-September-2015 or earlier based on customer acceptance

ASSESSMENT:

The same Bill Of Material is used for the assembly in NFME and in Infineon Technologies Malacca.

Product Quality and Reliability remains the same as proven by product qualification.

Product data sheets with all electrical characteristics remain unchanged

Package Outer Dimensions are within the datasheet package drawing.

DOCUMENTATION:		
	1_cip_15021a	List of affected products
	3_cip_15021a	Package Visual appearance

PCN 2015-021-A

Implementation of TO220 Fullpak in
Nantong Fujitsu Microelectronics Co., Ltd.
(NFME) for IGBT and Diode products



Sales Name	Current SP number	OPN	Package
IDV08E65D2	SP000994148	IDV08E65D2XKSA1	PG-TO220-2
IDV15E65D2	SP001005460	IDV15E65D2XKSA1	PG-TO220-2
IGA03N120H2	SP000215371	IGA03N120H2XKSA1	PG-TO220-3
IGA30N60H3	SP000853272	IGA30N60H3XKSA1	PG-TO220-3
IKA06N60T	SP000215375	IKA06N60TXKSA1	PG-TO220-3
IKA08N65F5	SP000973414	IKA08N65F5XKSA1	PG-TO220-3
IKA08N65H5	SP001001722	IKA08N65H5XKSA1	PG-TO220-3
IKA10N60T	SP000215376	IKA10N60TXKSA1	PG-TO220-3
IKA15N60T	SP000215377	IKA15N60TXKSA1	PG-TO220-3
IKA15N65F5	SP000973416	IKA15N65F5XKSA1	PG-TO220-3
IKA15N65H5	SP001001724	IKA15N65H5XKSA1	PG-TO220-3

Customer Information Package

3_cip15021a

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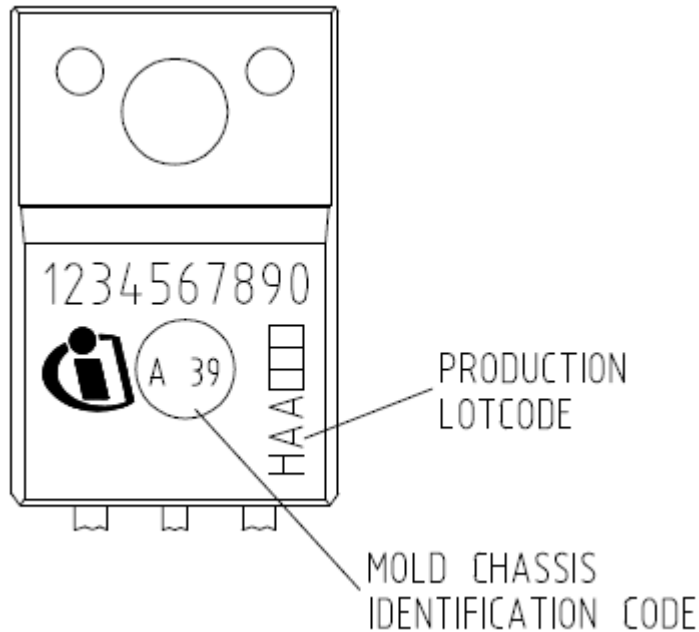
Implementation of TO220 Fullpak in Nantong Fujitsu
Microelectronics Co., Ltd. (NFME) for IGBT and Diode
products

2015-05-15

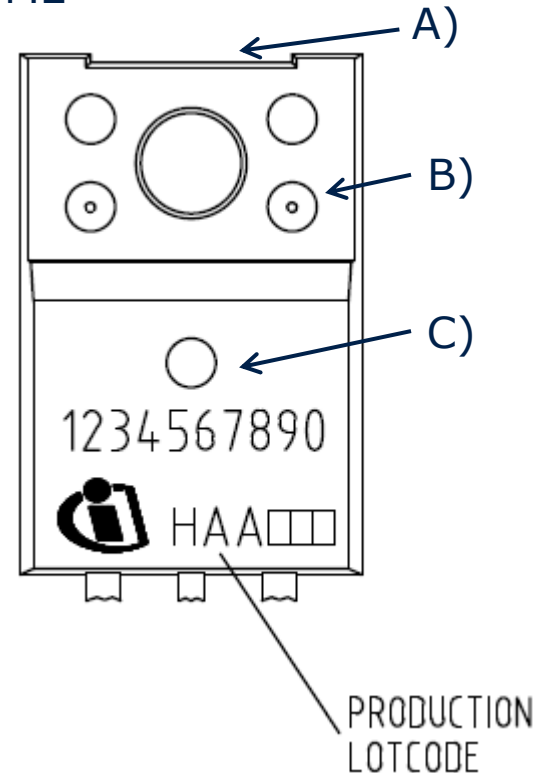


Package Visual Appearance

Infineon Malacca



NFME



- ❑ NFME's package has
 - A) a special mold gate slot
 - B) two extra round marks – from the filling process
 - C) different ejector pin mark size and location



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